MIMIX BROADBAND

February 2007 - Rev 19-Feb-07

CMM1434-SM XRoHS

Features

- → 34.5 dBm (Typ.) Saturated Output Power
- ★ 31.0 dB (Typ.) Linear Gain
- ★ Fully Matched
- ★ Uncondtionally Stable
- ★ Low-Cost, Surface Mount Package
- ★ Optimum Thermal Dissipation

General Description

The CMM1434-SM is a four-stage pHEMT GaAs MMIC power amplifier that is ideally suited for transmit subsystems designed for Ku-Band VSAT applications. The CMM1434-SM provides 31.0 dB linear gain and delivers 2.5 watts of output power at saturation operating from 13.5 to 14.5 GHz frequency.

The unconditional stability and internal matching provides for reduction of external components making this product a simple and low-cost solution. The low-cost 6mm x 6mm x 1.6mm surface mount package offers the same excellent RF and thermal properties as a typical flange package.



Applications

X Ku-Band VSAT Transmit Subsystems

Electrical Characteristics (T = $+25^{\circ}$ C, Vd = 6V, Idq = 1.5A)

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Parameter	Condition	Min	Тур	Max	Units
Frequency Range		13.50		14.50	GHz
Output Power	@ 1dB compression	31.5	32		dB m
Saturated Output Power	Pin = 10 dBm	33	34.5		dB m
Saturated Output Power Variation	Over operating frequency		0.5	1.0	dB m
Linear Gain		27.0	30.5	34.0	dB
Linear Gain Variation	Over operating frequency		1.0	3.0	dB
Input Reflection Coefficient			-10.0		dB
Output Reflection Coefficient			-7.0		dB
Gate Supply Voltage	Idq = 1.5A	-1.1	-0.9	-0.7	V olts
Drain Current	At Saturation		1.7	1.9	A
Power Added Efficiency	At Saturation		26		%

Electrical Specifications (TA = -40°C to +75°C)

Parameter	Condition	Min	Тур	Max	Units
Saturated Output Power	Variation from Room Temperature	-0.5			dB m
Linear Gain	Variation from Room Temperature	-2.5		3.5	dB
Stability		Unconditionally stable			

Maximum Ratings (TA = -40°C to +75°C) Operation outside these limits can cause permanent damage.

Parameter	Тур	Units	Parameter	Тур	Units
Drain Voltage (+V _{dd})	8.5	Volts	RF Input Power (P in)	15	dBm
Gate Voltage (V _{qq})	-3.0	V olts	Dissipated Power (P _{diss})	10	Watts
Quiescent Current (I _{dq})	2.1	Α	Storage Temperature	-50 to +150	°C
Gate Current (I _g)	5	mA	Operating Backside Temperature	-40 to +75	°C

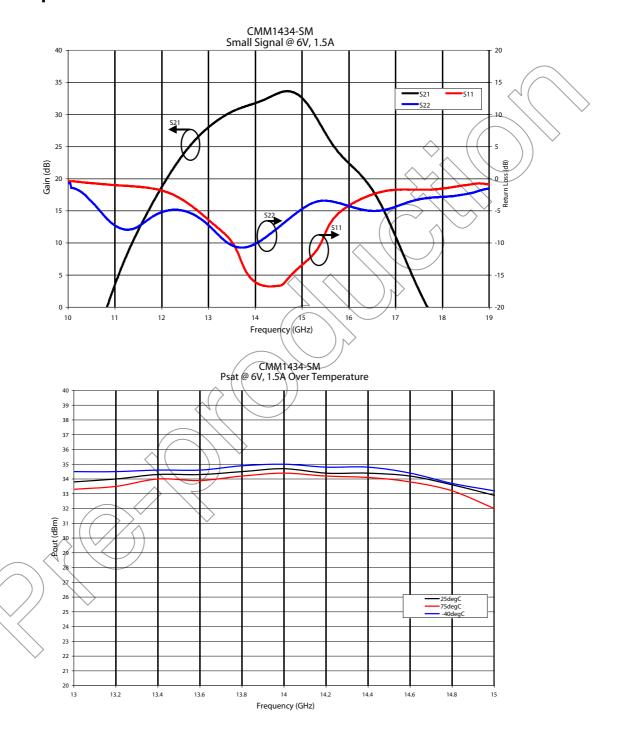
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Power Amplifier Measurements

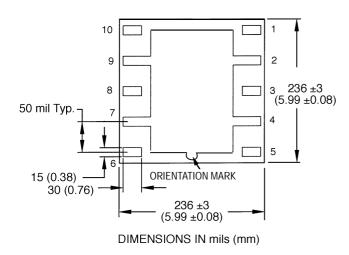


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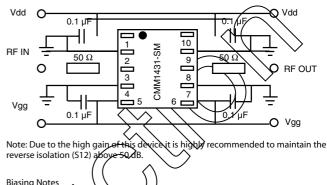
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Physical Dimensions (Bottom View)



Recommended Application Circuit

Note: This schematic represents the topology of the application circuit recommended by Celeritek.



- 2. 0.1µF bypass cap ed on PC board as close as possible to pins 0.1µF bypass canocious 3.1, 5, 6 and 10.

 1, 5, 6 and 10.

 Rositive (A) bias can be applied either at pin 1 or pin 6.

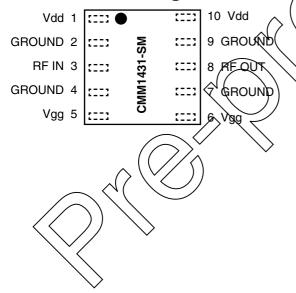
 Regative (-) bias can be applied either at pin 5 or pin 6.

 No DC block is required at RF IN/OUT.

 Regative (-) bias must be applied before applying positive (+) bias.

1. Dual bias is required

Pin Functional Diagram





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Handling and Assembly Information

CAUTION! - Mimix Broadband MMIC Products contain gallium arsenide (GaAs) which can be hazardous to the human body and the environment. For safety, observe the following procedures:

- Do not ingest.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Observe government laws and company regulations when discarding this product. This product must be discarded in accordance with methods specified by applicable hazardous waste procedures.

Life Support Policy - Mimix Broadband's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President and General Counsel of Mimix Broadband. As used herein: (1) Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user. (2) A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ESD - Gallium Arsenide (GaAs) devices are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic containers, which should be opened in cleanroom conditions at an appropriately grounded antistatic workstation. Devices need careful handling using correctly designed collets, vacuum pickups or, with care, sharp tweezers.

Die Attachment - GaAs Products from Mimix Broadband are 0.100 mm (0.004") thick and have vias through to the backside to enable grounding to the circuit. Microstrip substrates should be brought as close to the die as possible. The mounting surface should be clean and flat. If using conductive epoxy, recommended epoxies are Ablestick 84-1LMI or 84-1LMIT cured in a nitrogen atmosphere per manufacturer's cure schedule. Apply epoxy sparingly to avoid getting any on to the top surface of the die. An epoxy fillet should be visible around the total die periphery. If eutectic mounting is preferred, then a fluxless gold-tin (AuSn) preform, approximately 0.001² thick, placed between the die and the attachment surface should be used. A die bonder that utilizes a heated collet and provides scrubbing action to ensure total wetting to prevent void formation in a nitrogen atmosphere is recommended. The gold-tin eutectic (80% Au 20% Sn) has a melting point of approximately 280° C (Note: Gold Germanium should be avoided). The work station temperature should be 310° C +/- 10° C. Exposure to these extreme temperatures should be kept to minimum. The collet should be heated, and the die pre-heated to avoid excessive thermal shock. Avoidance of air bridges and force impact are critical during placement.

Wire Bonding - Windows in the surface passivation above the bond pads are provided to allow wire bonding to the die's gold bond pads. The recommended wire bonding procedure uses 0.076 mm x 0.013 mm (0.003" x 0.0005") 99.99% pure gold ribbon with 0.5-2% elongation to minimize RF port bond inductance. Gold 0.025 mm (0.001") diameter wedge or ball bonds are acceptable for DC Bias connections. Aluminum wire should be avoided. Thermo-compression bonding is recommended though thermosonic bonding may be used providing the ultrasonic content of the bond is minimized. Bond force, time and ultrasonics are all critical parameters. Bonds should be made from the bond pads on the die to the package or substrate. All bonds should be as short as possible.

Ordering Information

The CMM1434-SM is available in available in tube or tape and reel.

<u>Part Number for Ordering</u> <u>Package</u>

CMM 1431-SM Surface mount package

CMM1434-SM-0G0T Matte tin plated RoHS compliant surface mount package in tape and reel

PB-CMM1434-SM Evaluation Board

We also offer this product with SnPb (Tin-Lead) or NiPdAu plating. Please contact your regional sales manager for more information regarding different plating types.

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